



IPC-A-600H-2010

# Acceptability of Printed Boards

Developed by the IPC-A-600 Task Group (7-31a) of the Product Assurance Committee (7-30) of IPC

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Users of this publication are encouraged to participate in the development of future revisions.

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# Table of Contents

|  |  |
|--|--|
| <p><b>Acknowledgment</b> ..... i</p> <p><b>1 Introduction</b> ..... 1</p> <p><b>1.1 Scope</b> ..... 1</p> <p><b>1.2 Purpose</b> ..... 1</p> <p><b>1.3 Approach To This Document</b> ..... 1</p> <p><b>1.4 Classification</b> ..... 1</p> <p><b>1.5 Acceptance Criteria</b> ..... 2</p> <p><b>1.6 Applicable Documents</b> ..... 3</p> <p style="padding-left: 20px;">1.6.1 IPC ..... 3</p> <p style="padding-left: 20px;">1.6.2 American Society of Mechanical Engineers ..... 3</p> <p><b>1.7 Dimensions and Tolerances</b> ..... 3</p> <p><b>1.8 Terms and Definitions</b> ..... 3</p> <p><b>1.9 Revision Level Changes</b> ..... 3</p> <p><b>1.10 Workmanship</b> ..... 3</p> <p><b>2 Externally Observable Characteristics</b> ..... 4</p> <p><b>2.1 Printed Board Edges</b> ..... 4</p> <p style="padding-left: 20px;">2.1.1 Burrs ..... 4</p> <p style="padding-left: 40px;">2.1.1.1 Nonmetallic Burrs ..... 5</p> <p style="padding-left: 40px;">2.1.1.2 Metallic Burrs ..... 6</p> <p style="padding-left: 20px;">2.1.2 Nicks ..... 7</p> <p style="padding-left: 20px;">2.1.3 Haloing ..... 8</p> <p><b>2.2 Base Material Surface</b> ..... 9</p> <p style="padding-left: 20px;">2.2.1 Weave Exposure ..... 10</p> <p style="padding-left: 20px;">2.2.2 Weave Texture ..... 11</p> <p style="padding-left: 20px;">2.2.3 Exposed/Disrupted Fibers ..... 12</p> <p style="padding-left: 20px;">2.2.4 Pits and Voids ..... 13</p> <p><b>2.3 Base Material Subsurface</b> ..... 14</p> <p style="padding-left: 20px;">2.3.1 Measling ..... 17</p> <p style="padding-left: 20px;">2.3.2 Cracking ..... 18</p> <p style="padding-left: 20px;">2.3.3 Delamination/Blister ..... 20</p> <p style="padding-left: 20px;">2.3.4 Foreign Inclusions ..... 22</p> <p><b>2.4 Solder Coatings and Fused Tin Lead</b> ..... 24</p> <p style="padding-left: 20px;">2.4.1 Nonwetting ..... 24</p> <p style="padding-left: 20px;">2.4.2 Dewetting ..... 25</p> <p><b>2.5 Holes – Plated-Through – General</b> ..... 27</p> <p style="padding-left: 20px;">2.5.1 Nodules/Burrs ..... 27</p> <p style="padding-left: 20px;">2.5.2 Pink Ring ..... 28</p> <p style="padding-left: 20px;">2.5.3 Voids – Copper Plating ..... 29</p> <p style="padding-left: 20px;">2.5.4 Voids – Finished Coating ..... 30</p> <p style="padding-left: 20px;">2.5.5 Lifted Lands – (Visual) ..... 31</p> <p style="padding-left: 20px;">2.5.6 Cap Plating of Filled Holes – (Visual) ..... 32</p> <p><b>2.6 Holes – Unsupported</b> ..... 34</p> <p style="padding-left: 20px;">2.6.1 Haloing ..... 34</p> | <p><b>2.7 Printed Contacts</b> ..... 35</p> <p style="padding-left: 20px;">2.7.1 Surface Plating – Plated Contacts ..... 35</p> <p style="padding-left: 40px;">2.7.1.1 Surface Plating – Wire Bond Pads .... 37</p> <p style="padding-left: 20px;">2.7.2 Burrs on Edge-Board Contacts ..... 39</p> <p style="padding-left: 20px;">2.7.3 Adhesion of Overplate ..... 40</p> <p><b>2.8 Marking</b> ..... 41</p> <p style="padding-left: 20px;">2.8.1 Etched Marking ..... 42</p> <p style="padding-left: 20px;">2.8.2 Screened or Ink Stamped Marking .... 44</p> <p><b>2.9 Solder Mask</b> ..... 46</p> <p style="padding-left: 20px;">2.9.1 Coverage Over Conductors (Skip Coverage) ..... 47</p> <p style="padding-left: 20px;">2.9.2 Registration to Holes (All Finishes) ..... 48</p> <p style="padding-left: 20px;">2.9.3 Registration to Other Conductive Patterns ..... 49</p> <p style="padding-left: 40px;">2.9.3.1 Ball Grid Array (Solder Mask-Defined Lands) ..... 50</p> <p style="padding-left: 40px;">2.9.3.2 Ball Grid Array (Copper-Defined Lands) ..... 51</p> <p style="padding-left: 40px;">2.9.3.3 Ball Grid Array (Solder Dam) ..... 52</p> <p style="padding-left: 20px;">2.9.4 Blisters/Delamination ..... 53</p> <p style="padding-left: 20px;">2.9.5 Adhesion (Flaking or Peeling) ..... 55</p> <p style="padding-left: 20px;">2.9.6 Waves/Wrinkles/Ripples ..... 56</p> <p style="padding-left: 20px;">2.9.7 Tenting (Via Holes) ..... 57</p> <p style="padding-left: 20px;">2.9.8 Soda Strawing ..... 58</p> <p><b>2.10 Pattern Definition – Dimensional</b> ..... 60</p> <p style="padding-left: 20px;">2.10.1 Conductor Width and Spacing ..... 60</p> <p style="padding-left: 40px;">2.10.1.1 Conductor Width ..... 61</p> <p style="padding-left: 40px;">2.10.1.2 Conductor Spacing ..... 62</p> <p style="padding-left: 20px;">2.10.2 External Annular Ring – Measurement ..... 63</p> <p style="padding-left: 20px;">2.10.3 External Annular Ring – Supported Holes ..... 64</p> <p style="padding-left: 20px;">2.10.4 External Annular Ring – Unsupported Holes ..... 66</p> <p><b>2.11 Flatness</b> ..... 67</p> <p><b>3 Internally Observable Characteristics</b> ..... 69</p> <p><b>3.1 Dielectric Materials</b> ..... 70</p> <p style="padding-left: 20px;">3.1.1 Laminate Voids/Cracks (Outside Thermal Zone) ..... 70</p> <p style="padding-left: 20px;">3.1.2 Registration/Conductor to Holes ..... 72</p> <p style="padding-left: 20px;">3.1.3 Clearance Hole, Unsupported, to Power/Ground Planes ..... 73</p> <p style="padding-left: 20px;">3.1.4 Delamination/Blister ..... 74</p> <p style="padding-left: 20px;">3.1.5 Etchback ..... 75</p> <p style="padding-left: 40px;">3.1.5.1 Etchback ..... 76</p> <p style="padding-left: 40px;">3.1.5.2 Negative Etchback ..... 78</p> <p style="padding-left: 20px;">3.1.6 Smear Removal ..... 79</p> |
|--|--|

## Table of Contents (cont.)

|   |  |
|---|--|
| <ul style="list-style-type: none"> <li>3.1.7 Dielectric Material, Clearance,<br/>Metal Plane for Supported Holes ..... 81</li> <li>3.1.8 Layer-to-Layer Spacing ..... 82</li> <li>3.1.9 Resin Recession ..... 83</li> <li>3.1.10 Hole Wall Dielectric/Plated Barrel<br/>Separation (Hole Wall Pullaway) ..... 84</li> <li><b>3.2 Conductive Patterns – General</b> ..... 85</li> <li>3.2.1 Etching Characteristics ..... 86</li> <li>3.2.2 Print and Etch ..... 88</li> <li>3.2.3 Surface Conductor Thickness<br/>(Foil Plus Plating) ..... 89</li> <li>3.2.4 Foil Thickness – Internal Layers ..... 90</li> <li><b>3.3 Plated-Through Holes – General</b> ..... 91</li> <li>3.3.1 Annular Ring – Internal Layers ..... 93</li> <li>3.3.2 Lifted Lands – (Cross-Sections) ..... 95</li> <li>3.3.3 Foil Crack – (Internal Foil)<br/>“C” Crack ..... 96</li> <li>3.3.4 Foil Crack (External Foil) ..... 97</li> <li>3.3.5 Plating Crack (Barrel) “E” Crack ..... 98</li> <li>3.3.6 Plating Crack – (Corner) “F” Crack ... 99</li> <li>3.3.7 Plating Nodules ..... 100</li> <li>3.3.8 Copper Plating Thickness –<br/>Hole Wall ..... 101</li> <li>3.3.9 Copper Wrap Plating ..... 102</li> <li>3.3.10 Plating Voids ..... 104</li> <li>3.3.11 Solder Coating Thickness<br/>(Only When Specified) ..... 105</li> <li>3.3.12 Solder Mask Thickness ..... 106</li> <li>3.3.13 Wicking ..... 107</li> <li>3.3.13.1 Wicking, Clearance Holes ..... 108</li> <li>3.3.14 Innerlayer Separation – Vertical<br/>(Axial) Microsection ..... 109</li> <li>3.3.15 Innerlayer Separation – Horizontal<br/>(Transverse) Microsection ..... 110</li> <li>3.3.16 Material Fill of Blind and<br/>Buried Vias ..... 111</li> <li>3.3.17 Cap Plating of Filled Holes ..... 113</li> <li><b>3.4 Plated-Through Holes – Drilled</b> ..... 115</li> <li>3.4.1 Burrs ..... 116</li> <li>3.4.2 Nailheading ..... 117</li> <li><b>3.5 Plated-Through Holes – Punched</b> ..... 118</li> <li>3.5.1 Roughness and Nodules ..... 119</li> <li>3.5.2 Flare ..... 120</li> <li><b>4 Miscellaneous</b> ..... 121</li> <li><b>4.1 Flexible and Rigid-Flex Printed Boards</b> ..... 122</li> <li>4.1.1 Coverlay Coverage – Coverfilm<br/>Separations ..... 123</li> </ul> | <ul style="list-style-type: none"> <li>4.1.2 Coverlay/Covercoat Coverage –<br/>Adhesives ..... 124</li> <li>4.1.2.1 Adhesive Squeeze-Out –<br/>Land Area ..... 124</li> <li>4.1.2.2 Adhesive Squeeze-Out –<br/>Foil Surface ..... 125</li> <li>4.1.3 Access Hole Registration for<br/>Coverlay and Stiffeners ..... 126</li> <li>4.1.4 Plating Defects ..... 127</li> <li>4.1.5 Stiffener Bonding ..... 128</li> <li>4.1.6 Transition Zone, Rigid Area to<br/>Flexible Area ..... 129</li> <li>4.1.7 Solder Wicking/Plating<br/>Penetration Under Coverlay ..... 130</li> <li>4.1.8 Laminate Integrity ..... 131</li> <li>4.1.8.1 Laminate Integrity – Flexible<br/>Printed Board ..... 132</li> <li>4.1.8.2 Laminate Integrity – Rigid-Flex<br/>Printed Board ..... 133</li> <li>4.1.9 Etchback (Type 3 and<br/>Type 4 Only) ..... 134</li> <li>4.1.10 Smear Removal (Type 3 and<br/>4 Only) ..... 135</li> <li>4.1.11 Trimmed Edges/Edge<br/>Delamination ..... 136</li> <li>4.1.12 Fold/Bend Marks ..... 138</li> <li>4.1.13 Silver Film Integrity ..... 139</li> <li><b>4.2 Metal Core Printed Boards</b> ..... 141</li> <li>4.2.1 Type Classifications ..... 142</li> <li>4.2.2 Spacing Laminated Type ..... 143</li> <li>4.2.3 Insulation Thickness, Insulated<br/>Metal Substrate ..... 144</li> <li>4.2.4 Insulation Material Fill, Laminated<br/>Type Metal Core ..... 145</li> <li>4.2.5 Cracks in Insulation Material Fill,<br/>Laminated Type ..... 146</li> <li>4.2.6 Core Bond to Plated-Through<br/>Hole Wall ..... 147</li> <li><b>4.3 Flush Printed Boards</b> ..... 148</li> <li>4.3.1 Flushness of Surface Conductor .... 148</li> <li><b>5 Cleanliness Testing</b> ..... 149</li> <li><b>5.1 Solderability Testing</b> ..... 150</li> <li>5.1.1 Plated-Through Holes (Applicable<br/>to Test C/C1) ..... 151</li> <li><b>5.2 Electrical Integrity</b> ..... 152</li> </ul> |
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# 1 INTRODUCTION

## Introduction

### 1.1 SCOPE

This document describes the preferred, acceptable, and non-conforming conditions that are either externally or internally observable on printed boards. It represents the visual interpretation of minimum requirements set forth in various printed board specifications, e.g.; IPC-6010 series, J-STD-003, etc.

### 1.2 PURPOSE

The visual illustrations in this document portray specific criteria of the requirements of current IPC specifications. In order to properly apply and use the content of this document, the printed board should comply with the design requirements of the applicable IPC-2220 series document and the performance requirements of the applicable IPC-6010 series document. In the event the printed board does not comply with these or equivalent requirements, then the acceptance criteria should be as agreed between user and supplier (AABUS).

### 1.3 APPROACH TO THIS DOCUMENT

Characteristics are divided into two general groups:

- Externally Observable (section 2)
- Internally Observable (section 3)

**“Externally observable”** conditions are those features or imperfections which can be seen and evaluated on or from the exterior surface of the board. In some cases, such as voids or blisters, the actual condition is an internal phenomenon and is detectable from the exterior.

**“Internally observable”** conditions are those features or imperfections that require microsectioning of the specimen or other forms of conditioning for detection and evaluation. In some cases, these features may be visible from the exterior and require microsectioning in order to assess acceptability requirements.

Specimens should be illuminated during evaluation to the extent needed for effective examination. The illumination should be such that no shadow falls on the area of interest except those shadows caused by the specimen itself. It is recommended that polarization and/or dark field illumination be employed to prevent glare during the examination of highly reflective materials.

The illustrations in this document portray specific criteria relating to the heading and subheading of each page, with brief descriptions of the acceptable and nonconforming conditions for each product class. (See 1.4.) The visual quality acceptance criteria are intended to provide proper tools for the evaluation of visual anomalies. The illustrations and photographs in each situation are related to specific requirements.

The characteristics addressed are those that can be evaluated by visual observation and/or measurement of visually observable features.

Supported by appropriate user requirements, this document should provide effective visual criteria to quality assurance and manufacturing personnel.

This document cannot cover all of the reliability concerns encountered in the printed board industry; therefore, attributes not addressed in this issue **shall** be AABUS. The value of this document lies in its use as a baseline document that may be modified by expansions, exceptions, and variations which may be appropriate for specific applications.

When making accept and/or reject decisions, the awareness of documentation precedence must be maintained.

This document is a tool for observing how a product may deviate due to variation in processes. Refer to IPC-9191.

IPC-A-600 provides a useful tool for understanding and interpreting Automated Inspection Technology (AIT) results. AIT may be applicable to the evaluation of many of the dimensional characteristics illustrated in this document.

### 1.4 CLASSIFICATION

This standard recognizes that electrical and electronic products are subject to classifications by intended end-item use. Three general end-product classes have been established to reflect differences in producibility, complexity, functional performance requirements, and verification (inspection/test) frequency. It should be recognized that there may be overlaps of product between classes.

Process Indicator imperfections are permitted and are deliverable.

The user is responsible for defining the product class. The procurement documentation package **shall** state the product class and any exceptions to specific parameters, where appropriate.

Criteria defined in this document reflect three classes, which are as follows:

**Class 1** — Includes limited life products suitable for applications where the requirement is function of the completed product.

**Class 2** — Includes products where continued performance and extended life is required, and for which uninterrupted service is desired but not critical.

**Class 3** — Includes products where continued high performance or performance-on-demand is critical, product downtime cannot be tolerated, and the product must function when required.